

Product / Package Information

Package	MQFP
Body Size (mm)	10 X 10 X 2.0 (+3.2)
Lead Count	44
Terminal Finish	100 Sn
MS Number	MS011411A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.25E-01	86.91	869100	63.93		639322
Thermosets	Epoxy & Phenol Resin	Proprietary	4.78E-02	12.78	127800	9.40		94011
Other inorganic materials	Carbon black	1333-86-4	1.16E-03	0.31	3100	0.23		2280
Subtotal			3.74 E-01	100.00	1000000	73.56		735614

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.00 E-01	96.20	962000	19.69		196894
Copper & its alloys	Nickel	7440-02-0	3.12 E-03	3.00	30000	0.61		6140
Copper & its alloys	Silicon	7440-21-3	6.76 E-04	0.65	6500	0.13		1330
Copper & its alloys	Magnesium	7439-95-4	1.56 E-04	0.15	1500	0.03		307
Subtotal			1.04 E-01	100.00	1000000	20.47		204672

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.03 E-03	100.0	1000000	0.20		2026

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	6.15 E-03	100.0	1000000	1.21		12091

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.76 E-03	99.0	990000	0.35		3464
Precious metals	Palladium	7440-05-3	1.78 E-05	1.0	10000	0.00		35
Subtotal			1.78 E-03	100.0	1000000	0.35		3499

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.85 E-02	100.0	1000000	3.64		36396

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.19 E-03	75.47	754700	0.43		4304
Other organic materials	Epoxy resin	Proprietary	5.47 E-04	18.87	188700	0.11		1076
Other organic materials	Gamma Butyrolactone	96-48-0	8.20 E-05	2.83	28300	0.02		161
Others	Curing agent & hardener	Proprietary	8.20 E-05	2.83	28300	0.02		161
Subtotal			2.90 E-03	100.0	1000000	0.57		5702

Package Totals			Weight (g) 5.08 E-01			Percentage (%) 100		PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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